Abstracts

Series Interconnection of Six TRAPATT Devices on a Diamond Substrate

N.W. Cox, G.N. Hill, J.W. Amoss and C.T. Rucker. "Series Interconnection of Six TRAPATT Devices on a Diamond Substrate." 1976 MTT-S International Microwave Symposium Digest of Technical Papers 76.1 (1976 [MWSYM]): 45-47.

The effects of package parasitic on series interconnections of TRAPATT diode chips on diamond substrates have been studied via time domain computer simulations and experiments at frequencies from 2 to 9 GHz. Guidelines for the selection of package parasitic have been identified, and multichip series configurations, employing six chips mounted thermally in parallel on diamond, have been successfully demonstrated at 7.5 GHz with 35.5 watts output power.

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